Applicant: Hidetomo Miyake

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IN THE CLAIMS

Applicant respectfully requests that the claims of the above-identified application be amended so as to read as follows:

1. (Currently Amended) A substrate adsorbing device comprising:

a stage including an adsorption face for holding a substrate;

a plurality of adsorption ports formed in a region of the adsorption face of the stage;

an air discharge path connected to each of the adsorption ports;

pressure reducing means connected to the adsorption ports through the discharging path;

and

pressure detecting means that detects pressure in the air discharge path,

wherein a plurality of leak trenches open to both the adsorption face of the stage and

a side face of the stage are formed in a region of the stage except a region where

the adsorption ports are formed; wherein

the pressure detecting means is provided in the air discharge path for each

of the adsorption ports;

the leak trenches are formed in a grid pattern in the region of the

adsorption face of the stage; and

the adsorption ports are formed at centers of regions surrounded

by the leak trenches formed in the grid pattern, respectively.

- 2. (Canceled, without prejudice)
- 3. (Original) The substrate adsorption device of Claim 1,

wherein for each of the adsorption ports, the pressure detecting means and an opening/closing mechanism for opening/closing the corresponding adsorption port based on a pressure state detected by the corresponding pressure detecting means are provided in the air discharge path.

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- 4. (Original) The substrate adsorption device of Claim 3, wherein the opening/closing mechanism closes the corresponding adsorption port when the pressure detecting means does not detect a vacuum state.
- 5. (Cancled, without prejudice)
- 6. (Canceled, without prejudice)
- 7. (Canceled, without prejudice)
- 8. (Original) A substrate bonding device comprising:

two substrate adsorption devices according to Claim 1,

wherein the substrate adsorption devices are arranged so that the adsorption faces of the stages face each other, and

the stages are allowed to be close to each other while adsorbing and holding substrate, respectively, to bond the substrates to each other.